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RADEMARK			Filing Date		21 February 2002	
FORM			First Named Inventor		Pinarbasi et al.	
(to be used for all correspondence after Initial fillin			Art Unit		1765	
•			Examiner Name Deo			
Total Number of	Pages in This Submission	3	Attorney Docket Number	<b>SJ09</b>	920010155US1	
		ENC	LOSURES (Check all th	at apply	)	
Amendme A A A Extension Express Informatic Documen Response Incomple	fiter Final  ffidavits/declaration(s)  n of Time Request  Abandonment Request  on Disclosure Statement  Copy of Priority		Drawing(s)  Licensing-related Papers  Petition  Petition to Convert to a  Provisional Application  Power of Attorney, Revocation  Change of Correspondence Add  Terminal Disclaimer  Request for Refund  CD, Number of CD(s)	dress	After Allowance communication to Technology Center (TC)  Appeal Communication to Board of Appeals and Interferences Appeal Communication to TC (Appeal Notice, Brief, Reply Brief)  Proprietary Information  Status Letter Other Enclosure(s) (please Identify below):	
, Firms	SIGNA	TURE (	OF APPLICANT, ATTOR	NEY, C	OR AGENT	
Firm or Individual name			John J. Oskorep, B	lsq.		
Signature Signature						
Date		ार्ड	Apr. 1 2004			
	C	ERTIFIC	CATE OF TRANSMISSIO	N/MAI	LING	
I hereby certify the sufficient postage the date shown b	as first class mail in an en	eing facsi velope ad	mile transmitted to the USPTO dressed to: Commissioner for P	or depos atents, F	sited with the United States Postal Service with P.O. Box 1450, Alexandria, VA 22313-1450 on	
Typed or printed	name		John J. Oskorep, B	sq.		
Signature			~ (°C)~		Date 15 April 2000	

This collection of information is required by 37 CFR 1.5. The information is required to obtain or retain a benefit by the public which is to file (and by the USPTO to process) an application. Confidentiality is governed by 35 U.S.C. 122 and 37 CFR 1.14. This collection is estimated to 12 minutes to complete, including gathering, preparing, and submitting the completed application form to the USPTO. Time will vary depending upon the individual case. Any comments on the amount of time you require to complete this form and/or suggestions for reducing this burden, should be sent to the Chief Information Officer, U.S. Patent and Trademark Office, U.S. Department of Commerce, P.O. Box 1450, Alexandria, VA 22313-1450. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO: C mmissi ner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.



## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Applicat	tion of:	)	
	Pinarbasi et al.	) Group No.:	1765
Serial No.:	10/080,303	) Examiner:	Deo, Duy Vu Nguyen
Filed:	02/21/2002	) Docket No.:	SJO920010155US1

For: METHOD OF FORMING A READ SENSOR USING A LIFT-OFF MASK HAVING A HARDMASK LAYER AND A RELEASE LAYER

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

## RESPONSE TO RESTRICTION/ELECTION REQUIREMENT

In response to the Restriction Requirement mailed on March 16<sup>th</sup> 2004, please consider the following:

In the mailing of March 16<sup>th</sup> 2004, a Restriction Requirement was issued for the abovereferenced patent application. In the restriction requirement, the Examiner separated the claims

of the present application into two groups, namely Group I "method" claims 1-15 and Group II

"product" claims 16-20.

In response, the Applicants respectfully disagree with the Examiner and traverse the

Examiner's restriction. Group II product claims 16-20 are made by the same method recited in

method claim 1. As recited in product claim 16, the product is made by "forming a lift-off mask

over a central region of a sensor layer and then ion milling the sensor layer such that the end

portions of the sensor layer are removed and a central portion of the sensor layer remains, the

lift-off mask comprising a hardmask layer formed over a release layer." These are the same

limitations recited in claim 1.

The Examiner states that "in the instant case the product can be made by another and

materially different process such as a process using wet etch or RIE to remove the sensor layer."

However, claim 16 (product) and claim 1 (method) recite the same step of "ion milling" and

have the same scope with respect to "ion milling" even if an alternative process of wet etch or

RIE is utilized. In light of the above, the Applicants respectfully request the Examiner to

reconsider the position taken. In the event the Examiner continues to disagree, the Applicants

hereby elect GROUP I method claims 1-15 with traverse.

Thank you. The Examiner is invited to contact the undersigned by telephone if necessary

to expedite this matter.

Date: 15 April 2004

JOHN J. OSKOREP

Respectfully Submitted,

JOHN J. OSKOREP, ESQ.

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